26th IEEE International SoC Conference (SOCC)
September 04 – 06, 2013
Fraunhofer Institute for Integrated Circuits (IIS),
Erlangen (near Nuremberg), Germany

IEEE   **CALL FOR PAPERS**   **IEEE CIRCUITS AND SYSTEMS SOCIETY**

http://www.ieee-socc.org

The SOC Conference is a premier forum for sharing advances in SoC technologies and applications in the areas of digital systems, circuit architectures, design methods, tools, automation, manufacturing, test, and emerging technologies. The 26th SOCC will be held at Fraunhofer IIS in Erlangen, Germany and will offer three days of technical papers, technical workshops, a vendor exhibition and a "IIS-lab-tour". For updates and travel advice please check our website regularly http://www.ieee-socc.org or follow us on twitter "@ieee_socc" (or http://twitter.com/ieee_socc).
contact :   info@ieee-socc.org

SUBMISSION OF PAPERS AND WORKSHOP/TUTORIAL PROPOSALS
Electronic paper submissions are in *pdf* format, limited to **six** double-column IEEE format pages. The SOCC proceedings will be submitted to **IEEE *Xplore®*.** Embedded tutorial proposals with title, a half-page summary, and speaker's short bio are submitted to the Tutorial Chair

SOCC TECHNICAL SCOPE
Papers are invited which address new and previously unpublished results in the areas:
• Analog and Mixed-Signal Circuits and Systems
• Biomedical Circuits and Systems
• Wireline and Wireless Communication Circuits and Systems
• Digital Signal Processing (DSP) Circuits and Systems
• Low-Power, Green Circuits, Systems, and Design Methodologies
• Embedded Systems, Multi/Many Core Systems and Embedded Memory Technologies
• Network on Chip (NoC), Interconnects, and 3D-IC
• Reconfigurable and Programmable Circuits and Systems
• System Level Design Methodology and tools
• Design for Testability and Manufacturability
• Design Verification
• MEMS and Emerging Technologies

IMPORTANT DATES
Abstract and tutorial proposal submission deadline:	April 8th, 2013
Paper submission deadline:	April 15th, 2013
Notification of acceptance:	June 10th, 2013
Final camera-ready paper due:	June 24th, 2013

ORGANIZING COMMITTEE
Conference General Chair: *Norbert Schuhmann, Fraunhofer IIS*
Technical Program Chair: *Kaijian Shi, Cadence Design Systems*
Technical Program Co-Chair: *Nagi Naganathan, LSI Corp*
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